Zener Diode

DZ2712000L

# **Panasonic**

### DZ2712000L

## Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2S120 in SSSMini2 type package

#### ■ Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

#### ■ Marking Symbol:RJ

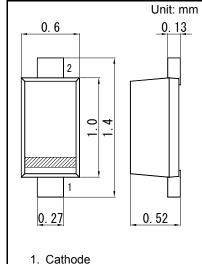
#### Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings Ta = 25 °C

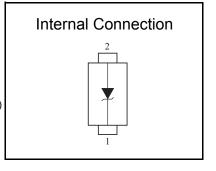
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	120	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm) Solder in (0.4 mm x 0.3 mm)



- 2. Anode

Panasonic	SSSMini2-F4-B
JEITA	SC-104A
Code	SOD-723



#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	11.40		12.60	V
Zener operating resistance	RZ	IZ = 5 mA			30	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω
Reverse current	IR	VR = 9.0 V			0.05	μΑ
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		9.3		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

- 2. Absolute frequency of input and output is 5 MHz.
- 3. \*1 The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C)
  - \*2 VZ guaranted 20 ms after current flow.
  - \*3 Tj = 25 °C to 150 °C

Established: 2010-02-10

: 2013-10-16

Revised

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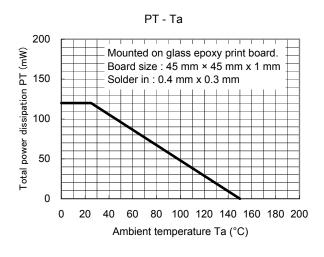
<sup>\*2:</sup> Test method:IEC61000 4 2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)

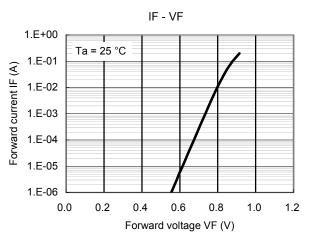
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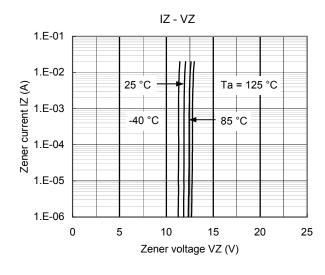
Zener Diode

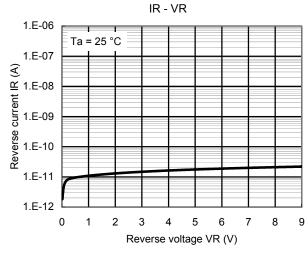
### DZ2712000L

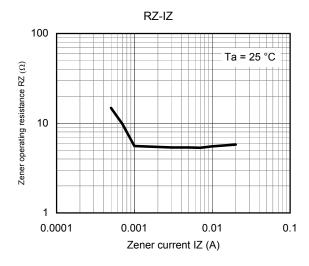
### Technical Data (reference)

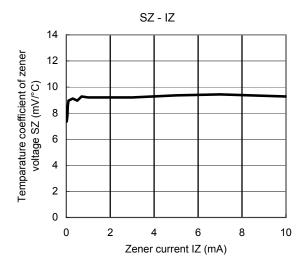












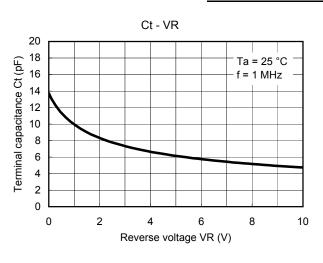
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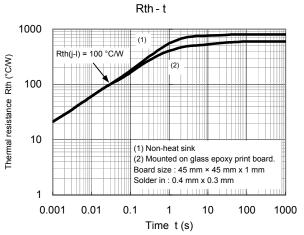
Established: 2010-02-10 Revised: 2013-10-16 **Panasonic** 

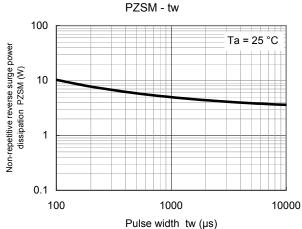
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## Technical Data (reference)







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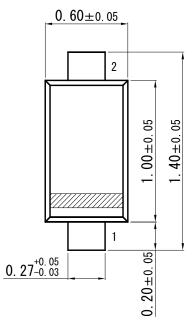
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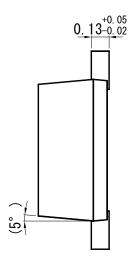
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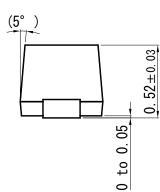
# SSSMini2-F4-B

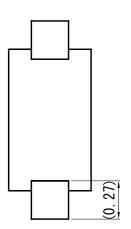
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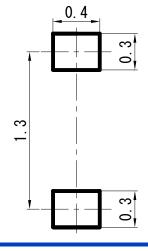








#### ■ Land Pattern (Reference) (Unit: mm)



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